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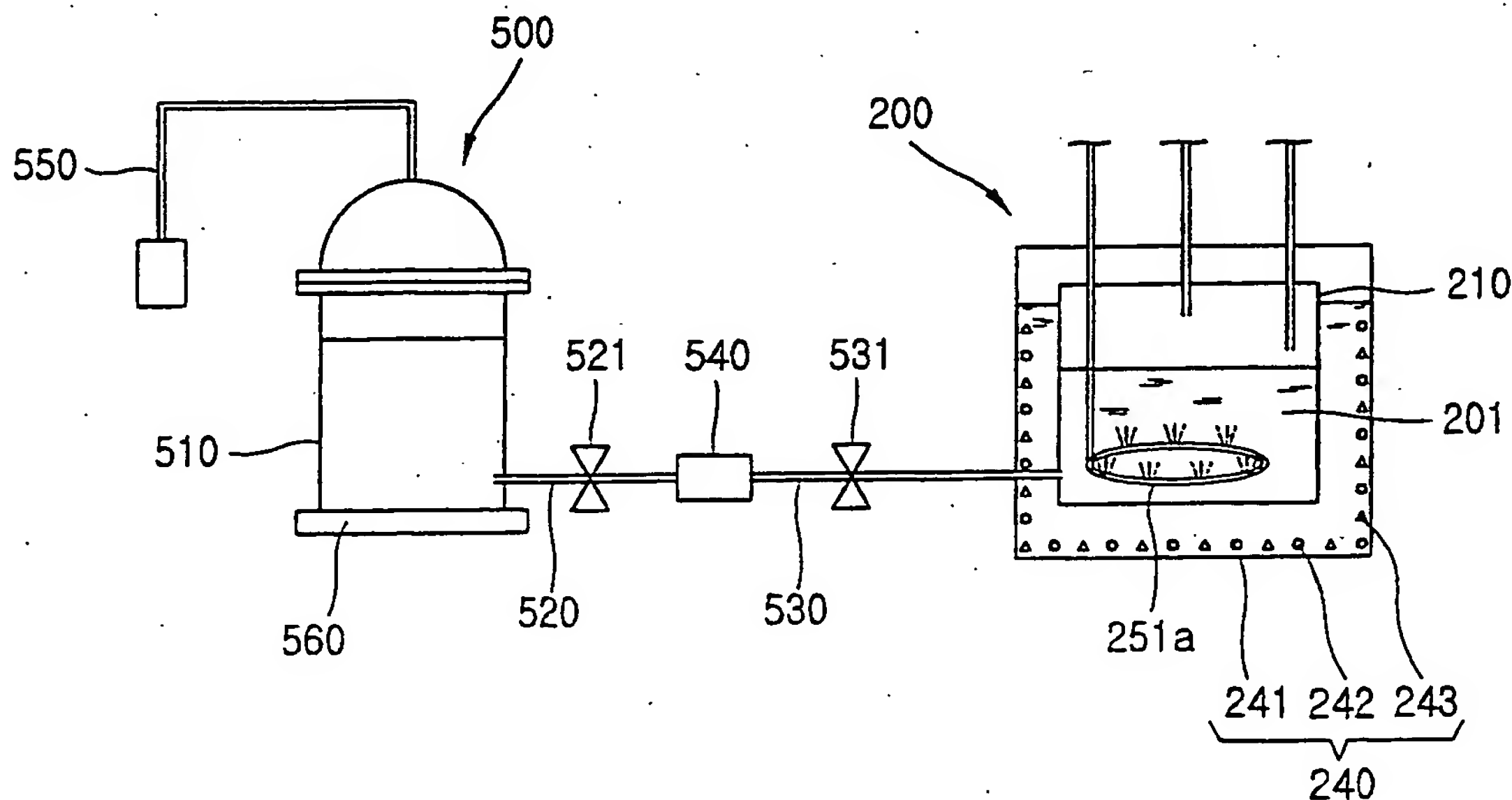
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(54) Title: PLASMA SURFACE PROCESSING SYSTEM AND SUPPLY DEVICE FOR PLASMA PROCESSING SOLUTION THEREFOR



(57) **Abstract:** Disclosed is a plasma surface processing system for processing a surface of an object to be processed (110) by forming plasma in a reaction chamber (100), the system including a supply device (230) for plasma processing solution (201) which supplies a processing material which forms plasma in a reaction chamber (100) into the reaction chamber as a liquid drop form.

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